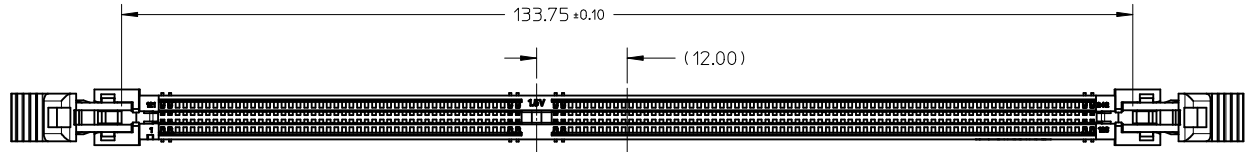


- NOTES:
1. MATERIAL : HOUSING - HIGH TEMP LCP, GLASS FILLED, UL 94V-0
COLOUR : SEE TABLE.
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE TABLE.
TERMINAL : COPPER ALLOY.
 2. FINISHES - SEE TABLE ON SHEET 2.
 3. PRODUCT SPECIFICATION : SEE TABLE.
 4. PRODUCT SHALL BE PACKED IN TRAY - SEE SHEET 5.
 5. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).

- 6 MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
- 7 MODULE SEATING PLANE FROM TOP OF PCB.
- 8 KEEP OUT ZONE RESERVED FOR LATCH.
- 9 KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDED LATCHES IN OPENING POSITION) IS MOUNTED ON THE PCB.
- 10 KEEP OUT ZONE AS PER JEDEC SO-007.
- 11, 12 FORKLOCK DETAIL VIEW.

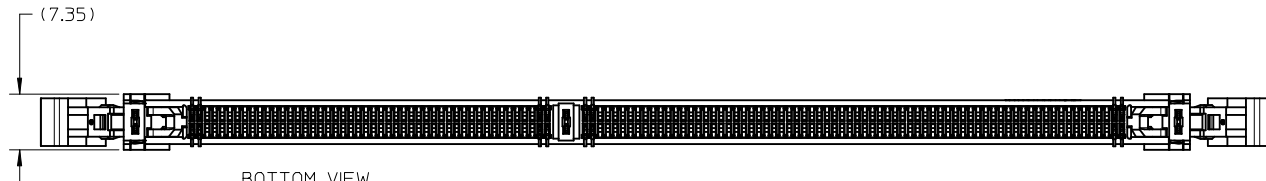
REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHYKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY: DWLEE01 CHECKED BY: YTYANG01 APPROVED BY: SHLENI	DATE: 2007/05/07 DATE: 2007/07/06 DATE: 2007/07/06	TITLE: DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT	molex MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ANGULAR ± 1 °	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78156-001	SHEET NO. 1 OF 6	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		A1	REV	SIZE A3					

10 9 8 7 6 5 4 3 2 1



TOP VIEW
(LATCHES ARE IN OPENING POSITION)

CENTER LINE OF 133.75 FEATURE

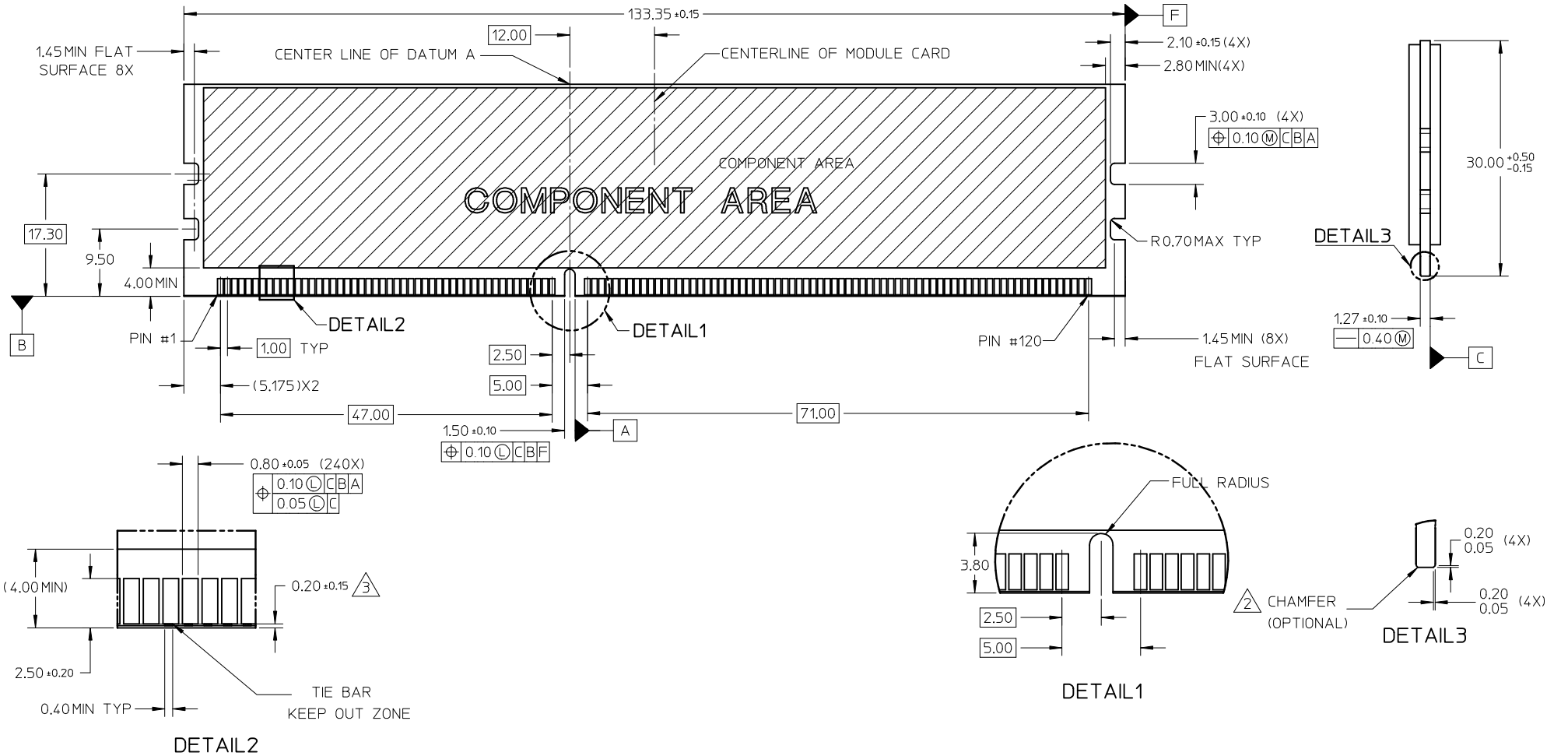


BOTTOM VIEW
(LATCHES ARE IN OPENING POSITION)

REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	DWLEE01	2007/05/07	DDR3 DIMM, 100MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS, VERTICAL SMT			
	2 PLACES	± 0.2	± ---	YTYANG01	2007/07/06	APPROVED BY				
	1 PLACE	± ---	± ---	SHLENI	2007/07/06	DATE				
	ANGULAR ± 1 °		MATERIAL NO.		DOCUMENT NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MOLEX INCORPORATED					
	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						SHEET NO.		
A1	A3							SD-78156-001		
								2 OF 6		

9 8 7 6 5 4 3 2 1

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL.
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS.
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	▽=0	mm	INCH	DRAWN BY	DATE	TITLE			
	∇=0	4 PLACES ± --- ± ---	DWLEE01	2007/05/07	DDR3 DIMM, 1.00MM PITCH				
		3 PLACES ± --- ± ---	CHECKED BY	DATE	240 CKTS, VERTICAL SMT				
	2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	YTYANG01	2007/07/06	APPROVED BY				
	ANGULAR ± 1 °		SHLENI	2007/07/06	MATERIAL NO.				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MOLEX INCORPORATED				
A1	REV			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
						DOCUMENT NO.		SHEET NO.	
						SD-78156-001		3 OF 6	

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

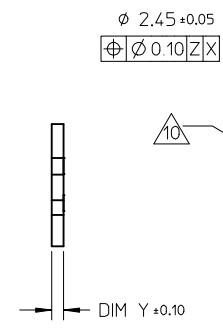
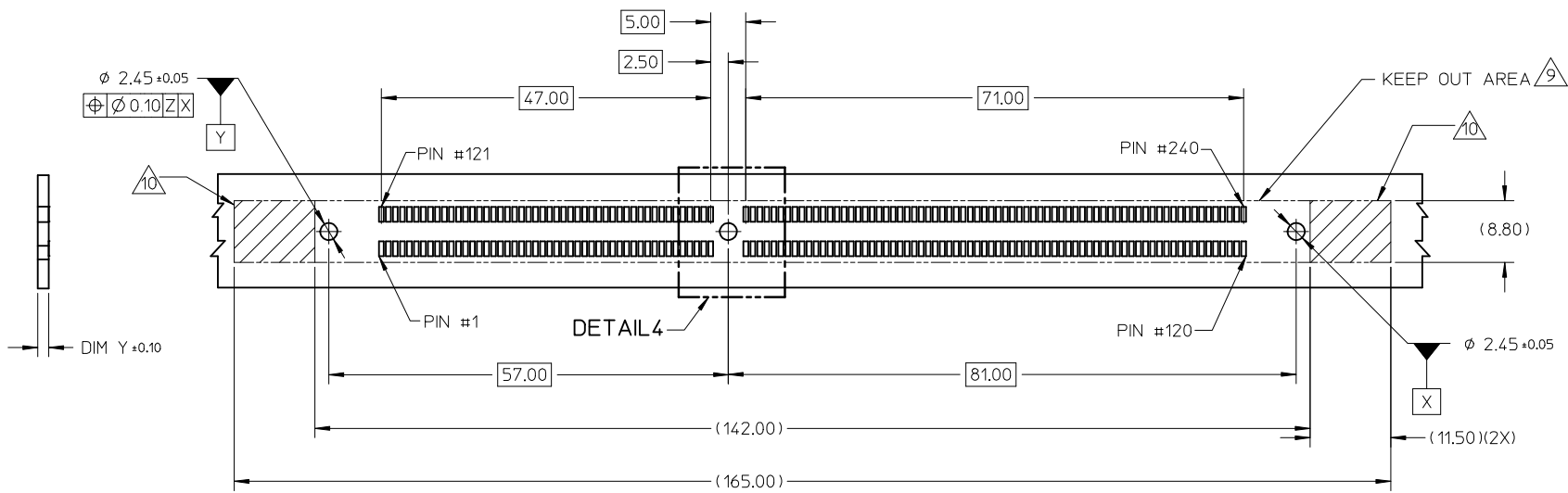
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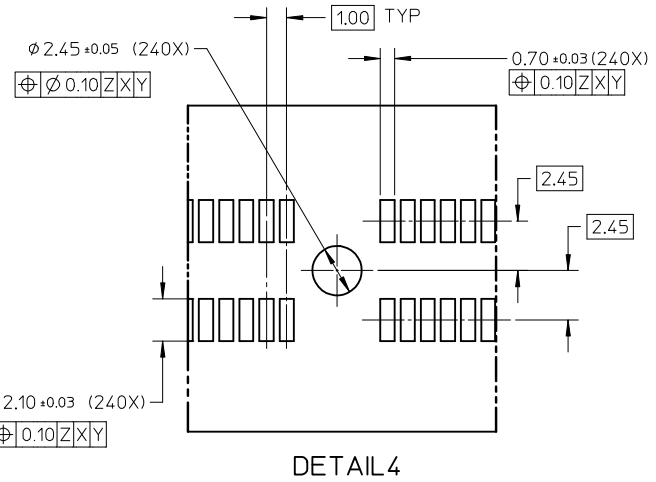
B

A



Z

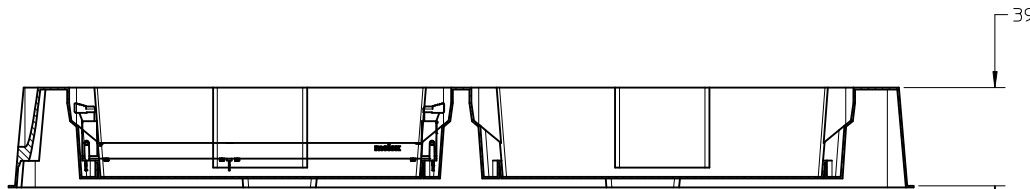
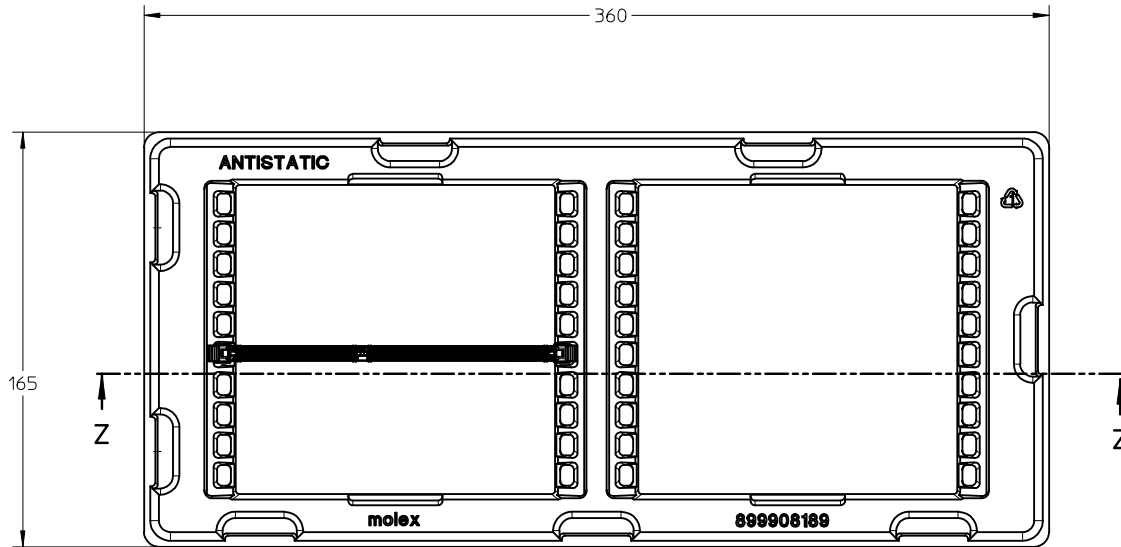
RECOMMENDED PCB THICKNESS 1.57MM TO 3.18MM
RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS



REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$\nabla=0$ $\square=0$		mm	INCH	DRAWN BY DWLEE01	DATE 2007/05/07	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT		
		4 PLACES	± ---	± ---	CHECKED BY YTYANG01	DATE 2007/07/06	APPROVED BY SHLENI 2007/07/06		
		3 PLACES	± ---	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78156-001		SHEET NO. 4 OF 6
	2 PLACES	± 0.2	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	1 PLACE	± ---	± ---	ANGULAR ± 1 °					

9 8 7 6 5 4 3 2 1

VIEW OF PACKAGING TRAY



SECTION Z-Z

NOTE:

1. CAVITY QTY ; 20PCS

REVISED IEC NO: S2009-0916 DRW:CMTEO CHKD:LG TAN APPR:SHLENI	2009/06/26 2009/06/26 2009/06/26	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	DRAWN BY DWLEE01 CHECKED BY YTYANG01 APPROVED BY SHLENI	DATE 2007/05/07 DATE 2007/07/06 DATE 2007/07/06	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT				
			ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	MOLEX INCORPORATED		SHEET NO. 5 OF 6	
	REVISED A1		REV DESCRIPTION			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DOCUMENT NO. SD-78156-001	

PART NO.	VOLTAGE KEY POS.	DIM X	PCB THICKNESS DIM Y (mm)	PLATING OPTION	HOUSING COLOUR	LATCH COLOUR	PRODUCT SPEC.
78156-0001	CENTER (1.5)	3.94	1.57 - 3.18	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK	PS-78156-001
78156-0003		3.94	1.57 - 3.18		NATURAL (IVORY)	NATURAL (IVORY)	
78156-0005		3.94	1.57 - 3.18		BLACK	NATURAL (IVORY)	
78156-0102		3.94	1.57 - 3.18	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	NATURAL (IVORY)	NATURAL (IVORY)	PS-78156-002

REVISED EC NO: S2009-0916 DRWN:CMTEO 2009/06/26 CHKD:CGTAN 2009/06/26 APPR:SHLENI 2009/06/26	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▼=0 □=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC	☉ □ THIRD ANGLE PROJECTION
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: DWLEE01 DATE: 2007/05/07 CHECKED BY: YTYANG01 DATE: 2007/07/06 APPROVED BY: SHLENI DATE: 2007/07/06	TITLE	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT	
	REV	SIZE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
A1	A3	SEE TABLE	SD-78156-001	6 OF 6		
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			